

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.01514	100.0	0.25513
			Subtotal	0.01514	100	0.25513
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.0078	5.0	0.1314
	Silver alloy	Silver (Ag)	7440-22-4	0.00234	1.5	0.03942
	Lead alloy	Lead (Pb)	7439-92-1	0.14582	93.5	2.45725
			Subtotal	0.15596	100	2.62807
Die	Doped silicon	Silicon (Si)	7440-21-3	0.17802	100.0	3
			Subtotal	0.17802	100	3
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.06056	100.0	1.02053
			Subtotal	0.06056	100	1.02053
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.06539	0.1	1.102
	Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.01962	0.03	0.3306
	Copper alloy	Copper (Cu)	7440-50-8	65.30884	99.87	1100.5674
			Subtotal	65.39385	100	1102
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.1347	100.0	2.27
			Subtotal	0.1347	100	2.27
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	1.53278	4.5	25.83
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	3.40618	10.0	57.4
	Filler	Silica fused	60676-86-0	25.54633	75.0	430.5
	Metal hydroxide	Metal hydroxide		3.40618	10.0	57.4
	Carbon Black	Carbon black	1333-86-4	0.17031	0.5	2.87
			Subtotal	34.06178	100	574
			Total	100.00001	100	1685.17373

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